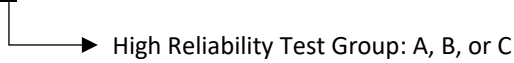
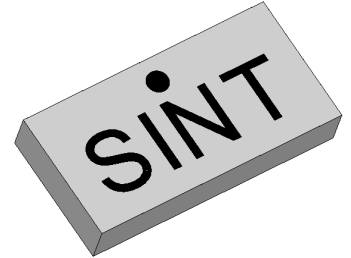


ORDERING INFORMATION**PART IDENTIFIER: HRYCTH0603ALN1SMTF**


High Reliability Test Group: A, B, or C

**SPECIFICATIONS****1. ELECTRICAL:**

Nominal Impedance:	50 Ω \pm 10%
Frequency Range:	DC – 67 GHz
Input Power CW:	1 W
Peak Power:	10 W (1 μ s pulse width/1% duty cycle)
*VSWR:	*1.25:1 Typical; 1.50:1 Max

**Note: When properly installed in a matched 50 Ω system per Smiths Interconnect recommended mounting criteria.*

2. ENVIRONMENTAL:

Operating Temperature:	-55°C to +150°C
Non-operating Temperature:	-65°C to +150°C
Temperature Coefficient:	\pm 200 PPM/°C Max

3. MARKING:

Unit Marking:	SINT with Dot Marking
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4. QUALITY ASSURANCE:

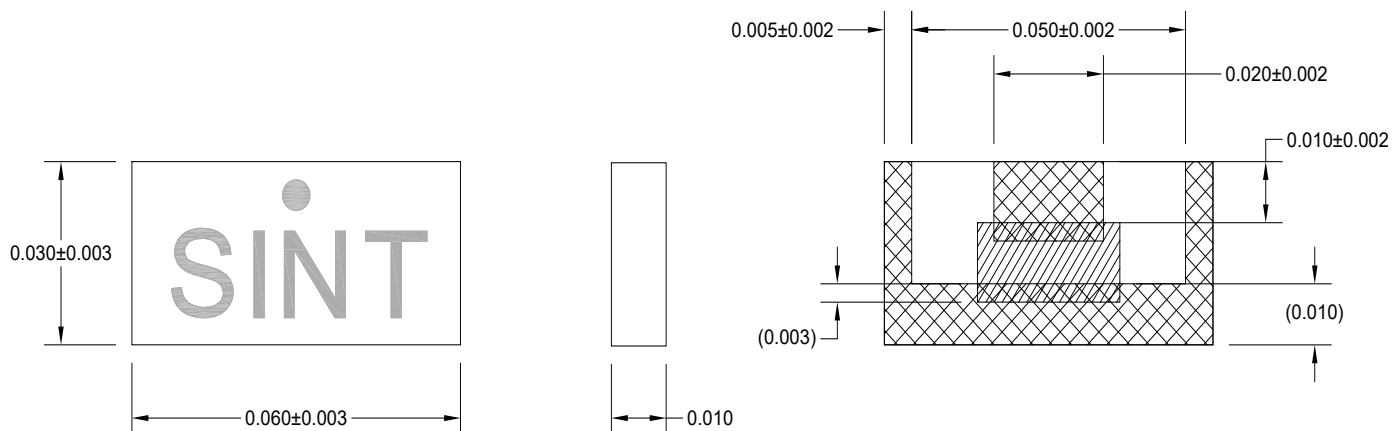
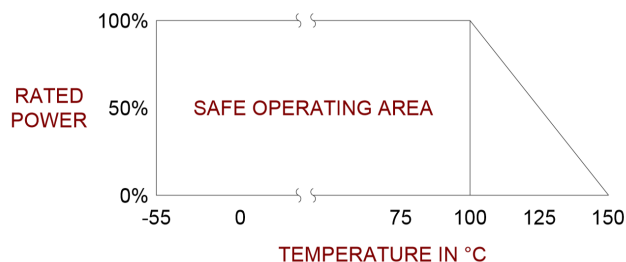
Sample Inspect Per ANSI/ASQC Z1.4 General Inspection, Level II, AQL=1.0.
 Visual and Mechanical Examination for Conformance to Outline Drawing Requirements.
 Measure DC Resistance.
 Data Retention - Standard

5. PACKAGING:

Standard:	Waffle or Tape and Reel
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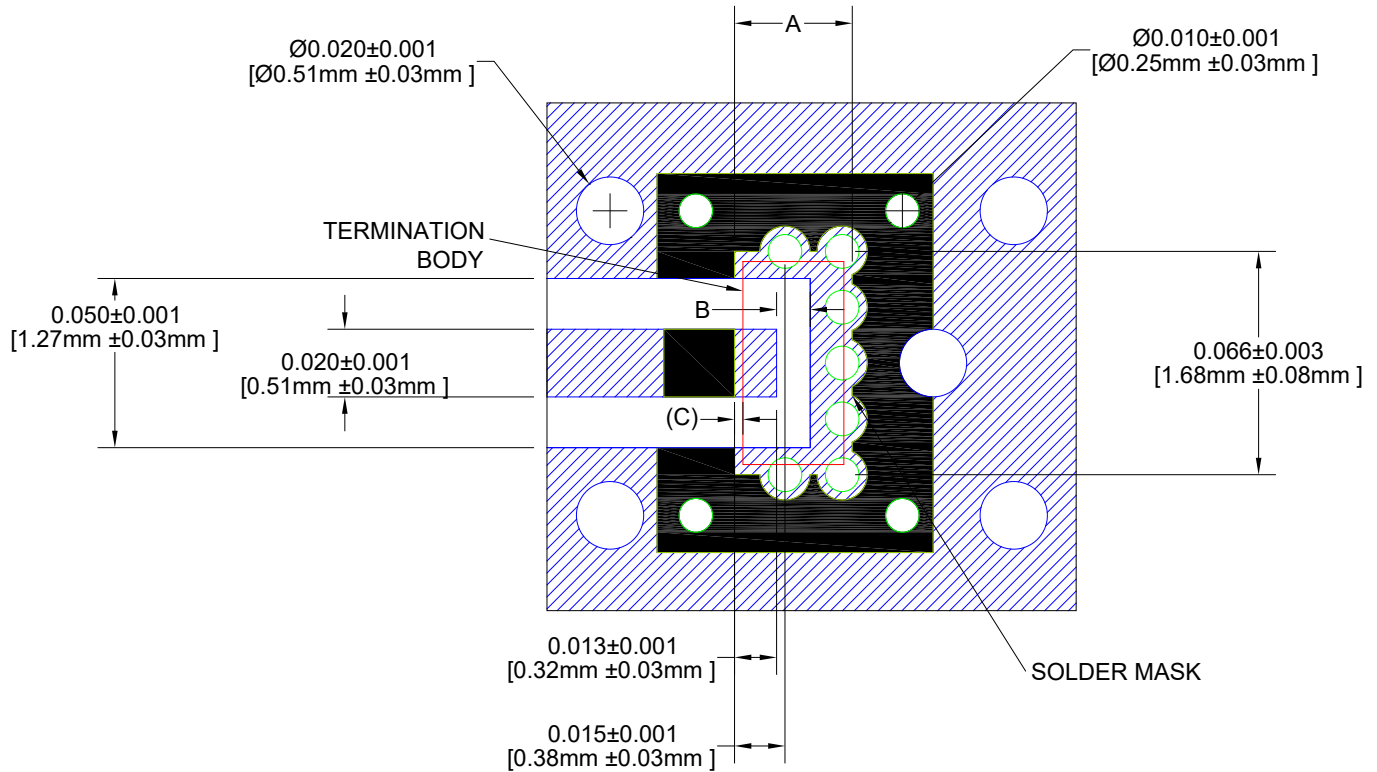
6. MECHANICAL:

Substrate Material:	Aluminum Nitride
Terminal Material:	Gold Over Nickel
Ground Bars:	Gold over Nickel
Resistive Element:	Thin Film, Tantalum Nitride
Metric Dimensions [mm]:	Provided for reference only



Unless Otherwise Specified Dimensions are in Inches: TOLERANCE: X.XX = ± 0.01 X.XXX = ± 0.005

7. FOOTPRINT:



DESIGN BASED ON MICROSTRIP, ROGERS 6035HTC, 0.010" SUBSTRATE

Dimension A = .035" is the Solder Mask width
 Dimension B = .010" is Transmission line end to GND plane
 Dimension C = (.0025") nominal, as it is the DUT- to-solder mask distance.